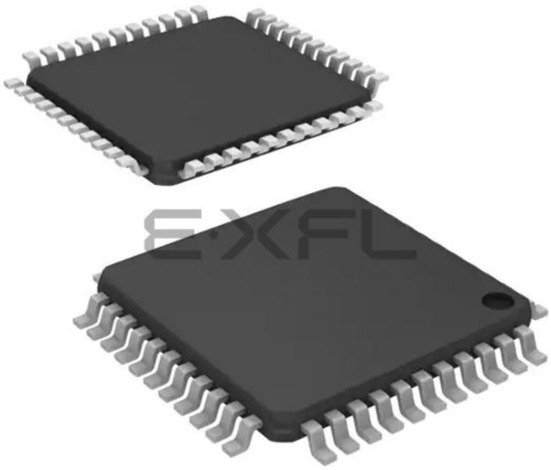

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx150f128d-i-pt

TABLE 5: PIN NAMES FOR 28-PIN GENERAL PURPOSE DEVICES

28-PIN QFN (TOP VIEW)(1,2,3.4)

PIC32MX110F016B
PIC32MX120F032B
PIC32MX130F064B
PIC32MX130F256B
PIC32MX150F128B
PIC32MX170F256B

28

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/RB0	15	TDO/RPB9/SDA1/CTED4/PMD3/RB9
2	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/RB1	16	V_{SS}
3	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/RB2	17	V_{CAP}
4	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/RB3	18	PGED2/RPB10/CTED11/PMD2/RB10
5	V_{SS}	19	PGEC2/TMS/RPB11/PMD1/RB11
6	OSC1/CLKI/RPA2/RA2	20	AN12/PMD0/RB12
7	OSC2/CLKO/RPA3/PMA0/RA3	21	AN11/RPB13/CTPLS/PMRD/RB13
8	SOSCI/RPB4/RB4	22	CV_{REFOUT}/AN10/C3INB/RPB14/SCK1/CTED5/PMWR/RB14
9	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	23	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
10	V_{DD}	24	AV_{SS}
11	PGED3/RPB5/PMD7/RB5	25	AV_{DD}
12	PGEC3/RPB6/PMD6/RB6	26	$\overline{MCLR}$
13	TDI/RPB7/CTED3/PMD5/INT0/RB7	27	V_{REF}+/CV_{REF}+/AN0/C3INC/RPA0/CTED1/RA0
14	TCK/RPB8/SCL1/CTED10/PMD4/RB8	28	V_{REF}-/CV_{REF}-/AN1/RPA1/CTED2/RA1

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 “Peripheral Pin Select”** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 “I/O Ports”** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to V_{SS} externally.

4: Shaded pins are 5V tolerant.

2.8.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- C_{IN} = PIC32_OSC2_Pin Capacitance = ~4-5 pF
- C_{OUT} = PIC32_OSC1_Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e.,12 mm length) = 2.5 pF

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer recommended: $C1 = C2 = 15\ pF$

Therefore:

$$C_{LOAD} = \{([C_{IN} + C1] * [C_{OUT} + C2]) / [C_{IN} + C1 + C2 + C_{OUT}] \} + \textit{estimated oscillator PCB stray capacitance}$$

$$= \{([5 + 15][5 + 15]) / [5 + 15 + 15 + 5] \} + 2.5\ pF$$

$$= \{([20][20]) / [40] \} + 2.5$$

$$= 10 + 2.5 = 12.5\ pF$$

Rounded to the nearest standard value or 12 pF in this example for Primary Oscillator crystals "C1" and "C2".

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

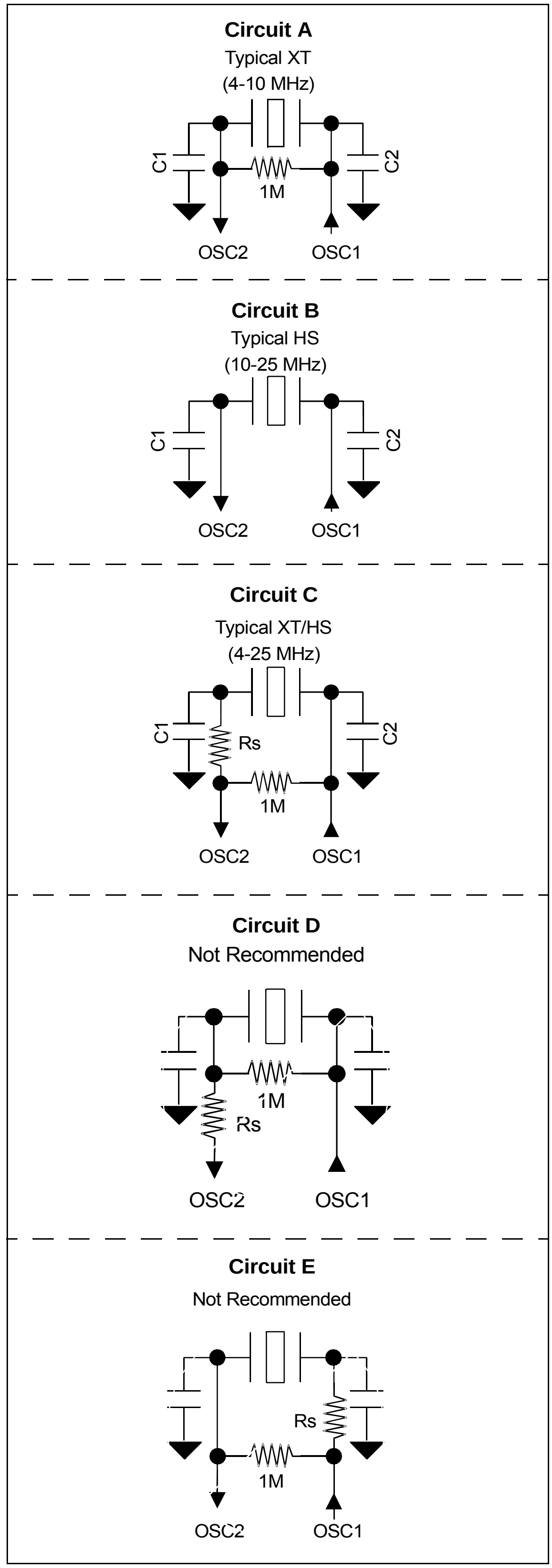
- Select a crystal with a lower "minimum" power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing "ESR" rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator. The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

Note:	Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor, RS, as shown in circuit "C" in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to ~V_{DD}-0.6V. When measuring the oscillator signal you must use a FET scope probe or a probe with ≤ 1.5 pF or the scope probe itself will unduly change the gain and peak-to-peak levels.

2.8.1.1 Additional Microchip References

- AN588 *"PICmicro® Microcontroller Oscillator Design Guide"*
- AN826 *"Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices"*
- AN849 *"Basic PICmicro® Oscillator Design"*

FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS



3.0 CPU

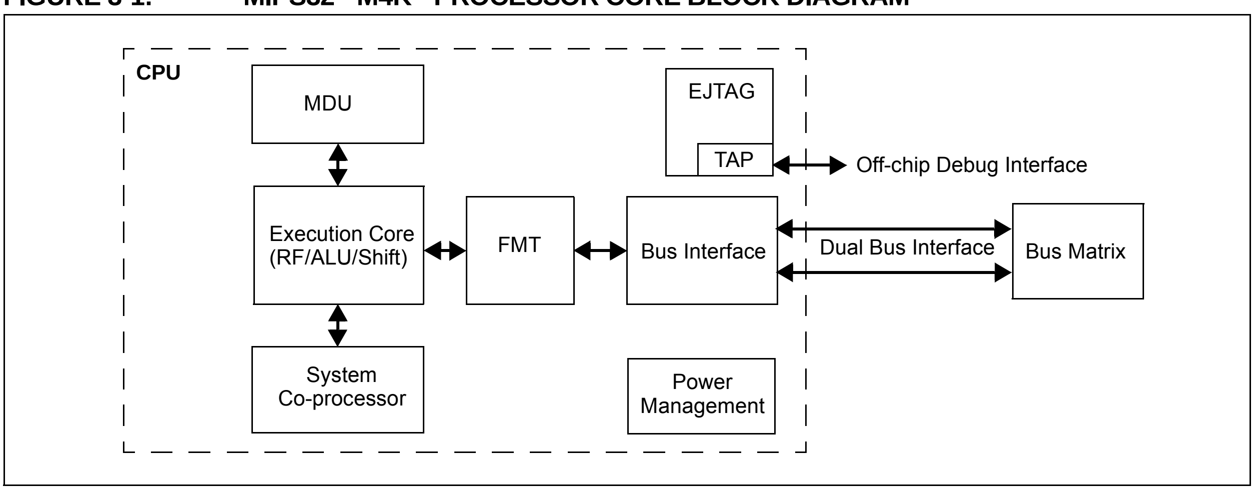
Note:	This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 2. "CPU"** (DS60001113), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32). Resources for the MIPS32® M4K® Processor Core are available at: www.imgtec.com.

The MIPS32® M4K® Processor Core is the heart of the PIC32MX1XX/2XX family processor. The CPU fetches instructions, decodes each instruction, fetches source operands, executes each instruction and writes the results of instruction execution to the destinations.

3.1 Features

- 5-stage pipeline
- 32-bit address and data paths
- MIPS32 Enhanced Architecture (Release 2)
  - Multiply-accumulate and multiply-subtract instructions
  - Targeted multiply instruction
  - Zero/One detect instructions
  - `WAIT` instruction
  - Conditional move instructions (`MOVN`, `MOVZ`)
  - Vectored interrupts
  - Programmable exception vector base
  - Atomic interrupt enable/disable
  - Bit field manipulation instructions
- MIPS16e® code compression
  - 16-bit encoding of 32-bit instructions to improve code density
  - Special PC-relative instructions for efficient loading of addresses and constants
  - `SAVE` and `RESTORE` macro instructions for setting up and tearing down stack frames within subroutines
  - Improved support for handling 8 and 16-bit data types
- Simple Fixed Mapping Translation (FMT) mechanism
- Simple dual bus interface
  - Independent 32-bit address and data buses
  - Transactions can be aborted to improve interrupt latency
- Autonomous multiply/divide unit
  - Maximum issue rate of one 32x16 multiply per clock
  - Maximum issue rate of one 32x32 multiply every other clock
  - Early-in iterative divide. Minimum 11 and maximum 33 clock latency (dividend (*rs*) sign extension-dependent)
- Power control
  - Minimum frequency: 0 MHz
  - Low-Power mode (triggered by `WAIT` instruction)
  - Extensive use of local gated clocks
- EJTAG debug and instruction trace
  - Support for single stepping
  - Virtual instruction and data address/value
  - Breakpoints

FIGURE 3-1: MIPS32® M4K® PROCESSOR CORE BLOCK DIAGRAM



4.2 Bus Matrix Control Registers

TABLE 4-2: BUS MATRIX REGISTER MAP

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2000	BMXCON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	BMXERRIXI	BMXERRICD	BMXERRDMA	BMXERRDS	BMXERRIS	001F
		15:0	—	—	—	—	—	—	—	—	—	BMXWSDRM	—	—	—	BMXARB<2:0>			0041
2010	BMXDKPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDKPBA<15:0>																0000
2020	BMXDUDBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUDBA<15:0>																0000
2030	BMXDUPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUPBA<15:0>																0000
2040	BMXDRMSZ	31:16	BMXDRMSZ<31:0>																xxxx
		15:0																	xxxx
2050	BMXPUPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	BMXPUPBA<19:16>				0000
		15:0	BMXPUPBA<15:0>																0000
2060	BMXPFMSZ	31:16	BMXPFMSZ<31:0>																xxxx
		15:0																	xxxx
2070	BMXBOOTSZ	31:16	BMXBOOTSZ<31:0>																0000
		15:0																	0C00

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

REGISTER 4-1: BMXCON: BUS MATRIX CONFIGURATION REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	—	—	—	BMX ERRIXI	BMX ERRICD	BMX ERRDMA	BMX ERRDS	BMX ERRIS
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	R/W-1	U-0	U-0	U-0	R/W-0	R/W-0	R/W-1
	—	BMX WSDRM	—	—	—	BMXARB<2:0>		

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared

bit 31-21 **Unimplemented:** Read as ‘0’

bit 20 **BMXERRIXI:** Enable Bus Error from IXI bit
1 = Enable bus error exceptions for unmapped address accesses initiated from IXI shared bus
0 = Disable bus error exceptions for unmapped address accesses initiated from IXI shared bus

bit 19 **BMXERRICD:** Enable Bus Error from ICD Debug Unit bit
1 = Enable bus error exceptions for unmapped address accesses initiated from ICD
0 = Disable bus error exceptions for unmapped address accesses initiated from ICD

bit 18 **BMXERRDMA:** Bus Error from DMA bit
1 = Enable bus error exceptions for unmapped address accesses initiated from DMA
0 = Disable bus error exceptions for unmapped address accesses initiated from DMA

bit 17 **BMXERRDS:** Bus Error from CPU Data Access bit (disabled in Debug mode)
1 = Enable bus error exceptions for unmapped address accesses initiated from CPU data access
0 = Disable bus error exceptions for unmapped address accesses initiated from CPU data access

bit 16 **BMXERRIS:** Bus Error from CPU Instruction Access bit (disabled in Debug mode)
1 = Enable bus error exceptions for unmapped address accesses initiated from CPU instruction access
0 = Disable bus error exceptions for unmapped address accesses initiated from CPU instruction access

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6 **BMXWSDRM:** CPU Instruction or Data Access from Data RAM Wait State bit
1 = Data RAM accesses from CPU have one wait state for address setup
0 = Data RAM accesses from CPU have zero wait states for address setup

bit 5-3 **Unimplemented:** Read as ‘0’

bit 2-0 **BMXARB<2:0>:** Bus Matrix Arbitration Mode bits
111 = Reserved (using these Configuration modes will produce undefined behavior)
•
•
•
011 = Reserved (using these Configuration modes will produce undefined behavior)
010 = Arbitration Mode 2
001 = Arbitration Mode 1 (default)
000 = Arbitration Mode 0

REGISTER 4-2: BMXDKPBA: DATA RAM KERNEL PROGRAM BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDKPBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDKPBA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘0’

bit 15-10 **BMXDKPBA<15:10>:** DRM Kernel Program Base Address bits
When non-zero, this value selects the relative base address for kernel program space in RAM

bit 9-0 **BMXDKPBA<9:0>:** Read-Only bits
This value is always ‘0’, which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernal mode data usage.
2: The value in this register must be less than or equal to BMXDRMSZ.

10.0 USB ON-THE-GO (OTG)

Note:	This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 27. "USB On-The-Go (OTG)"** (DS60001126), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The Universal Serial Bus (USB) module contains analog and digital components to provide a USB 2.0 Full-Speed and Low-Speed embedded host, Full-Speed device or OTG implementation with a minimum of external components. This module in Host mode is intended for use as an embedded host and therefore does not implement a UHCI or OHCI controller.

The USB module consists of the clock generator, the USB voltage comparators, the transceiver, the Serial Interface Engine (SIE), a dedicated USB DMA controller, pull-up and pull-down resistors, and the register interface. A block diagram of the PIC32 USB OTG module is presented in Figure 10-1.

The clock generator provides the 48 MHz clock required for USB Full-Speed and Low-Speed communication. The voltage comparators monitor the voltage on the VBUS pin to determine the state of the bus. The transceiver provides the analog translation between the USB bus and the digital logic. The SIE is a state machine that transfers data to and from the endpoint buffers and generates the hardware protocol for data transfers. The USB DMA controller transfers data between the data buffers in RAM and the SIE. The integrated pull-up and pull-down resistors eliminate the need for external signaling components. The register interface allows the CPU to configure and communicate with the module.

The PIC32 USB module includes the following features:

- USB Full-Speed support for Host and Device
- Low-Speed Host support
- USB OTG support
- Integrated signaling resistors
- Integrated analog comparators for VBUS monitoring
- Integrated USB transceiver
- Transaction handshaking performed by hardware
- Endpoint buffering anywhere in system RAM
- Integrated DMA to access system RAM and Flash

Note:	The implementation and use of the USB specifications, as well as other third party specifications or technologies, may require licensing; including, but not limited to, USB Implementers Forum, Inc., also referred to as USB-IF (www.usb.org). The user is fully responsible for investigating and satisfying any applicable licensing obligations.

REGISTER 10-11: U1CON: USB CONTROL REGISTER (CONTINUED)

bit 1 **PPBRST:** Ping-Pong Buffers Reset bit
1 = Reset all Even/Odd buffer pointers to the EVEN Buffer Descriptor banks
0 = Even/Odd buffer pointers are not Reset

bit 0 **USBEN:** USB Module Enable bit(4)
1 = USB module and supporting circuitry is enabled
0 = USB module and supporting circuitry is disabled

SOFEN: SOF Enable bit(5)
1 = SOF token is sent every 1 ms
0 = SOF token is disabled

Note 1: Software is required to check this bit before issuing another token command to the U1TOK register (see Register 10-15).

2: All host control logic is reset any time that the value of this bit is toggled.

3: Software must set RESUME for 10 ms if the part is a function, or for 25 ms if the part is a host, and then clear it to enable remote wake-up. In Host mode, the USB module will append a Low-Speed EOP to the RESUME signaling when this bit is cleared.

4: Device mode.

5: Host mode.

REGISTER 10-14: U1FRMH: USB FRAME NUMBER HIGH REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	R-0	R-0	R-0
	—	—	—	—	—	FRMH<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-3 **Unimplemented:** Read as ‘0’

bit 2-0 **FRMH<2:0>:** The Upper 3 bits of the Frame Numbers bits
The register bits are updated with the current frame number whenever a SOF TOKEN is received.

REGISTER 10-15: U1TOK: USB TOKEN REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	PID<3:0>(1)				EP<3:0>			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as ‘0’

bit 7-4 **PID<3:0>:** Token Type Indicator bits(1)
`1101` = SETUP (TX) token type transaction
`1001` = IN (RX) token type transaction
`0001` = OUT (TX) token type transaction
Note: All other values are reserved and must not be used.

bit 3-0 **EP<3:0>:** Token Command Endpoint Address bits
The four bit value must specify a valid endpoint.

Note 1: All other values are reserved and must not be used.

12.2 Timer1 Control Registers

TABLE 12-1: TIMER1 REGISTER MAP

Virtual Address (BF80_#)	Register Name[1]	Bit Range	Bits 31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
0600	T1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	TWDIS	TWIP	—	—	—	TGATE	—	TCKPS<1:0>		—	TSYNC	TCS	—	0000
0610	TMR1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR1<15:0>																0000
0620	PR1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR1<15:0>																FFFF

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 “CLR, SET and INV Registers”** for more information.

REGISTER 22-1: AD1CON1: ADC CONTROL REGISTER 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	ON(1)	—	SIDL	—	—	FORM<2:0>		
7:0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0, HSC	R/C-0, HSC
	SSRC<2:0>			CLRASAM	—	ASAM	SAMP(2)	DONE(3)

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** ADC Operating Mode bit(1)
- 1 = ADC module is operating
- 0 = ADC module is not operating

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
- 1 = Discontinue module operation when device enters Idle mode
- 0 = Continue module operation when the device enters Idle mode

bit 12-11 **Unimplemented:** Read as '0'

bit 10-8 **FORM<2:0>:** Data Output Format bits
- 111 = Signed Fractional 32-bit (DOUT = sddd dddd dd00 0000 0000 0000 0000)
- 110 = Fractional 32-bit (DOUT = dddd dddd dd00 0000 0000 0000 0000 0000)
- 101 = Signed Integer 32-bit (DOUT = ssss ssss ssss ssss ssss sssd dddd dddd)
- 100 = Integer 32-bit (DOUT = 0000 0000 0000 0000 0000 00dd dddd dddd)
- 011 = Signed Fractional 16-bit (DOUT = 0000 0000 0000 0000 sddd dddd dd00 0000)
- 010 = Fractional 16-bit (DOUT = 0000 0000 0000 0000 dddd dddd dd00 0000)
- 001 = Signed Integer 16-bit (DOUT = 0000 0000 0000 0000 ssss sssd dddd dddd)
- 000 =Integer 16-bit (DOUT = 0000 0000 0000 0000 0000 00dd dddd dddd)

bit 7-5 **SSRC<2:0>:** Conversion Trigger Source Select bits
- 111 = Internal counter ends sampling and starts conversion (auto convert)
- 110 = Reserved
- 101 = Reserved
- 100 = Reserved
- 011 = CTMU ends sampling and starts conversion
- 010 = Timer 3 period match ends sampling and starts conversion
- 001 = Active transition on INT0 pin ends sampling and starts conversion
- 000 = Clearing SAMP bit ends sampling and starts conversion

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ '0', this bit is automatically cleared by hardware to end sampling and start conversion.

3: This bit is automatically set by hardware when analog-to-digital conversion is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

NOTES:

TABLE 30-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	V_{OL}	**Output Low Voltage** I/O Pins	—	—	0.4	V	$I_{OL} \leq 10$ mA, $V_{DD} = 3.3V$
DO20	V_{OH}	**Output High Voltage** I/O Pins	1.5(1)	—	—	V	$I_{OH} \geq -14$ mA, $V_{DD} = 3.3V$
			2.0(1)	—	—		$I_{OH} \geq -12$ mA, $V_{DD} = 3.3V$
			2.4	—	—		$I_{OH} \geq -10$ mA, $V_{DD} = 3.3V$
			3.0(1)	—	—		$I_{OH} \geq -7$ mA, $V_{DD} = 3.3V$

Note 1: Parameters are characterized, but not tested.

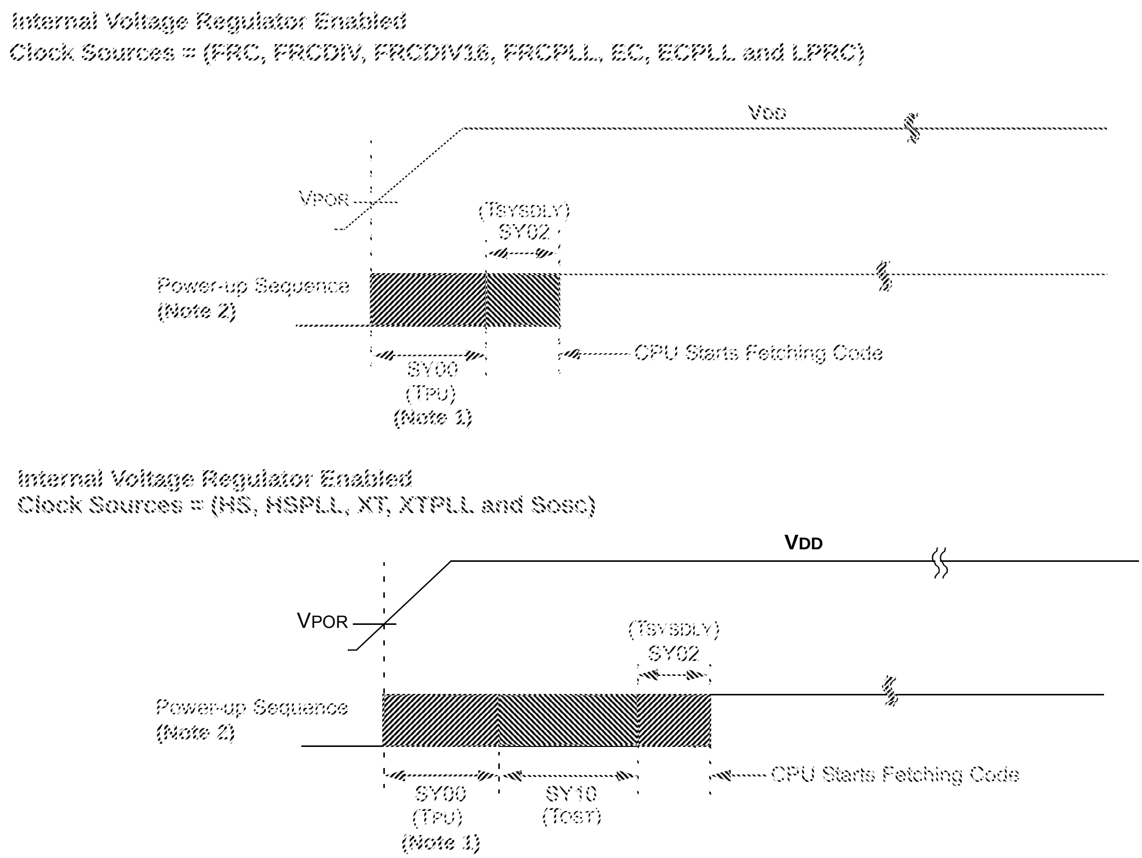
TABLE 30-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.(1)**	**Typical**	**Max.**	**Units**	**Conditions**
BO10	V_{BOR}	BOR Event on V_{DD} transition high-to-low(2)	2.0	—	2.3	V	—

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

2: Overall functional device operation at $V_{BORMIN} < V_{DD} < V_{DDMIN}$ is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below V_{DDMIN}.

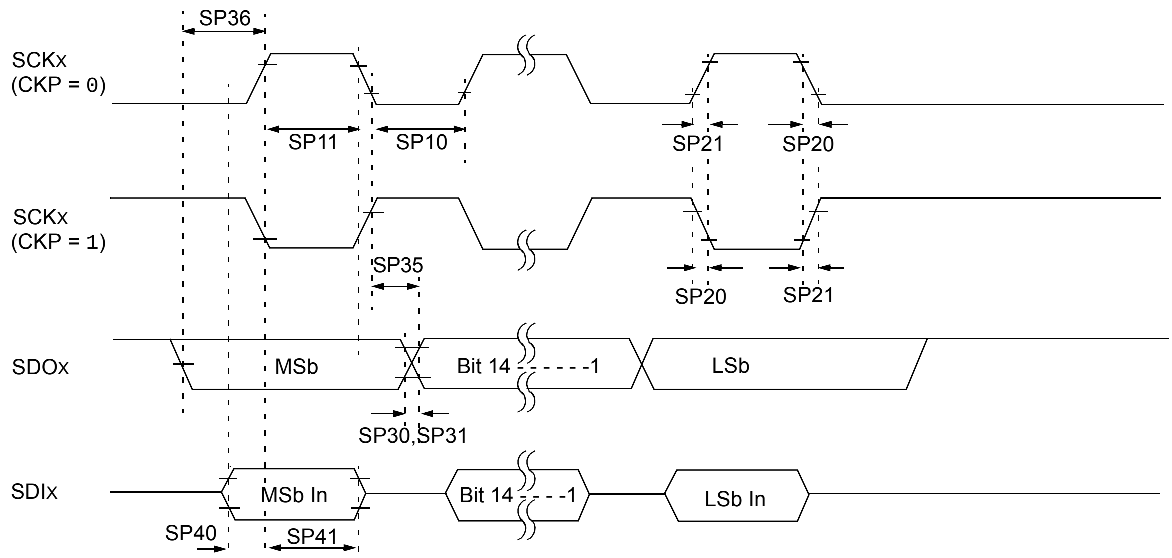
FIGURE 30-4: POWER-ON RESET TIMING CHARACTERISTICS



Note 1: The power-up period will be extended if the power-up sequence completes before the device exits from BOR (VDD < VDDMIN).

2: Includes interval voltage regulator stabilization delay.

FIGURE 30-11: SPIx MODULE MASTER MODE (CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-29: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP11	TscH	SCKx Output High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	15	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 30-13: SPIx MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS

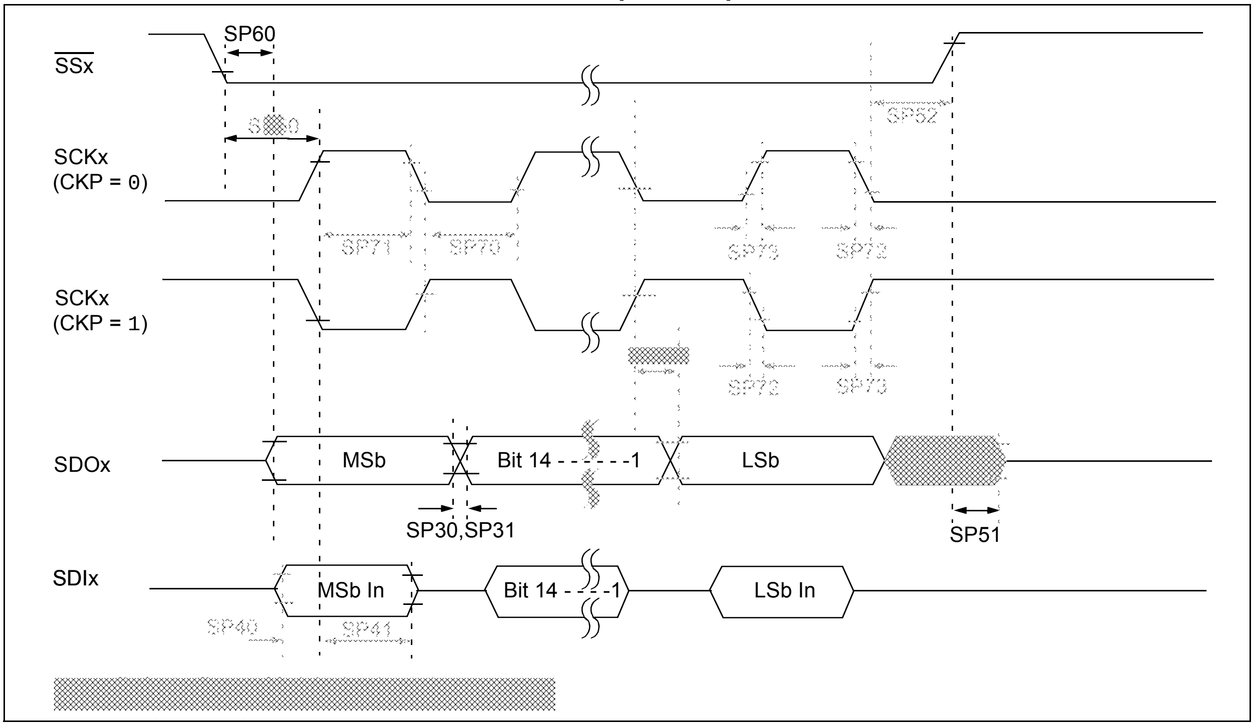


TABLE 30-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics[1]**	**Min.**	**Typical[2]**	**Max.**	**Units**	**Conditions**
SP70	TSCL	SCKx Input Low Time **(Note 3)**	TSCK/2	—	—	ns	—
SP71	TSCH	SCKx Input High Time **(Note 3)**	TSCK/2	—	—	ns	—
SP72	TSCF	SCKx Input Fall Time	—	5	10	ns	—
SP73	TSCR	SCKx Input Rise Time	—	5	10	ns	—
SP30	TDOF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TDOR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TSCH2DOV, TSCL2DOV	SDOx Data Output Valid after SCKx Edge	—	—	20	ns	VDD > 2.7V
			—	—	30	ns	VDD < 2.7V
SP40	TDIV2SCH, TDIV2SCL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TSCH2DIL, TSCL2DIL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TSSL2SCH, TSSL2SCL	$\overline{SSx}$ ↓ to SCKx ↓ or SCKx ↑ Input	175	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns.

4: Assumes 50 pF load on all SPIx pins.

TABLE 30-32: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TPB * (BRG + 2)	—	μs	—
			400 kHz mode	TPB * (BRG + 2)	—	μs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	μs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TPB * (BRG + 2)	—	μs	—
			400 kHz mode	TPB * (BRG + 2)	—	μs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	μs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 2)**	100	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	μs	—
			400 kHz mode	0	0.9	μs	
			1 MHz mode **(Note 2)**	0	0.3	μs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	TPB * (BRG + 2)	—	μs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	μs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	μs	After this period, the first clock pulse is generated
			400 kHz mode	TPB * (BRG + 2)	—	μs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	μs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	μs	—
			400 kHz mode	TPB * (BRG + 2)	—	μs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	μs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	ns	—
			400 kHz mode	TPB * (BRG + 2)	—	ns	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	ns	

Note 1: BRG is the value of the I^{2}C Baud Rate Generator.
2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).
3: The typical value for this parameter is 104 ns.

TABLE 31-3: DC CHARACTERISTICS: IDLE CURRENT (I_{IDLE})

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial	
Parameter No.	**Typical(2)**	**Max.**	**Units**	**Conditions**
Idle Current (I_{IDLE}): Core Off, Clock on Base Current (Note 1)				
MDC34a	8	13	mA	50 MHz

Note 1: The test conditions for I_{IDLE} current measurements are as follows:
- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Idle mode (CPU core Halted), and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD
- RTCC and JTAG are disabled

2: Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 31-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial		
Param. No.	**Typical(2)**	**Max.**	**Units**	**Conditions**	
Power-Down Current (I_{PD}) (Note 1)					
MDC40k	10	25	μA	-40°C	Base Power-Down Current
MDC40n	250	500	μA	+85°C	
Module Differential Current					
MDC41e	10	55	μA	3.6V	Watchdog Timer Current: ΔI_{WDT} **(Note 3)**
MDC42e	23	55	μA	3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} **(Note 3)**
MDC43d	1100	1300	μA	3.6V	ADC: ΔI_{ADC} **(Notes 3,4)**

Note 1: The test conditions for I_{PD} current measurements are as follows:
- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD
- RTCC and JTAG are disabled

2: Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

NOTES:

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